

TPS92665-Q1 具有高级诊断功能和集成振荡器的汽车类低噪声 16 通道 LED 矩阵管理器

1 特性

- 符合面向汽车应用的 AEC-Q100 标准
 - 1 级：-40°C 至 +125°C 环境温度
 - 器件 HBM 分类等级 H1C
 - 器件 CDM 分类等级 C5
- 功能安全型
 - 可提供用于功能安全系统设计的文档
- 16 个集成旁路开关
 - 可编程 10 位 PWM 调光
 - 可编程压摆率控制
 - LED 开路检测和保护
 - 单 LED 短路检测
- UART 串行通信
 - 用于系统时钟的内部振荡器
 - 用于同步器件的 LVDS 时钟驱动器
 - 兼容上一代 LMM
 - 兼容 CAN 收发器
- 集成 ADC
 - 每个开关的 LED 电压
 - 内核温度
 - 2x 通用 ADC 输入 (兼容热敏电阻)

2 应用

- 汽车前照灯系统
- ADB 或无眩光远光灯
- 连续转向、动画日间行车灯

3 说明

TPS92665 LED 矩阵管理器器件通过提供单个像素级 LED 控制来实现完全动态的自适应照明解决方案。该器件的 4 个串联集成开关各有 4 个子灯串，可绕过单个 LED。各个子灯串允许器件接受单个或多个电流源。

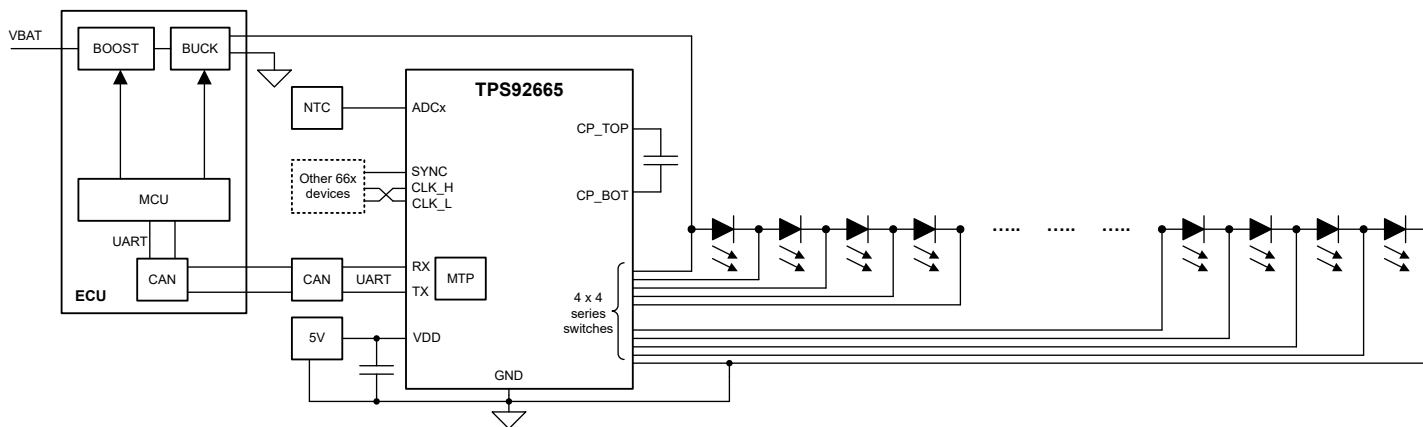
TPS92665 具有一个内部振荡器。内部振荡器可通过内部低噪声 LVDS 发送器和接收器块共享给其他系统器件。多点通用异步接收器发送器 (UART) 串行接口与 TPS92664、TPS92667、TPS92662x 和 TPS92663x 器件兼容。具有多路复用输入的板载 ADC 可对所有 LED 通道以及 IC 内核温度进行采样。该 ADC 还对专用 ADC 输入进行采样，可用于系统温度补偿、LED 分级和编码。

TPS92665 包含寄存器，可用于对灯串中单个 LED 的相移和脉冲宽度进行编程以及报告 LED 开路、短路故障和功能参数。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 (标称值)
TPS92665-Q1	PHP (HTQFP、48)	7.00mm × 7.00mm

- (1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



简化版应用



4 Device and Documentation Support

4.1 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

4.2 支持资源

[TI E2E™ 支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《[使用条款](#)》。

4.3 Trademarks

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4.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

4.5 术语表

TI 术语表

本术语表列出并解释了术语、首字母缩略词和定义。

5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS92665QPHPRQ1	Active	Production	HTQFP (PHP) 48	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	125 to -40	TPS92665Q
TPS92665QPHPRQ1.A	Active	Production	HTQFP (PHP) 48	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	125 to -40	TPS92665Q

- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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GENERIC PACKAGE VIEW

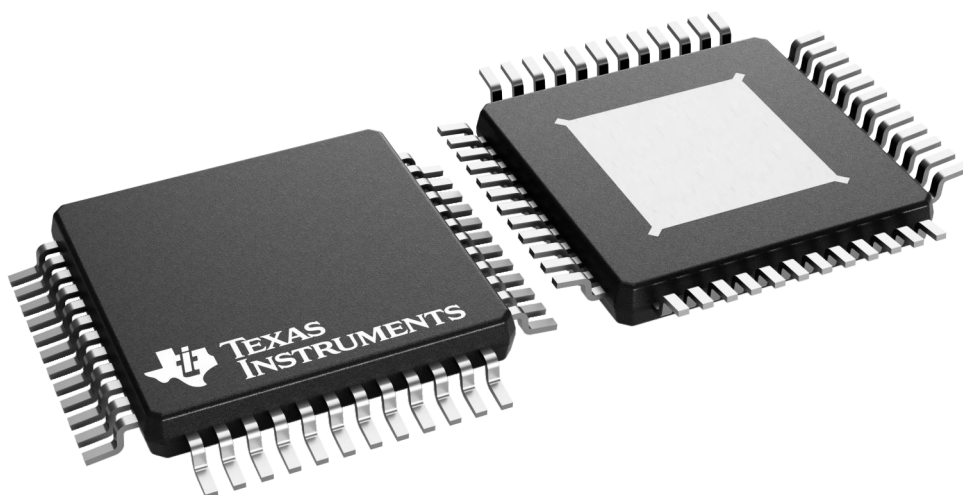
PHP 48

TQFP - 1.2 mm max height

7 x 7, 0.5 mm pitch

QUAD FLATPACK

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4226443/A



PowerPAD™ HTQFP - 1.2 mm max height

Technical drawing of a 48-pin Quad Flat Pack (QFP) component. The drawing includes a top view, a side view, and a detail view (Detail A).

Top View:

- Overall width: 7.2 mm (6.8 mm typical)
- Overall height: 9.2 mm (8.8 mm typical)
- Pin pitch: 0.5 mm
- Pin 1 ID (Identification Mark)
- Feature control frame: $\oplus 0.08 \text{ (M)} \text{ C A B}$
- Dimensions: 48X 0.27 / 0.17, 44X 0.5, 4X 5.5, 12, 13, 24, 25, 36, 37, 48

Side View:

- Maximum height: 1.2 MAX
- Seating Plane
- Feature control frame: 0.08
- Dimension: (0.13) TYP

Detail A (Typical):

- Gage Plane
- Width: 0.25 mm
- Length: 0.75 mm (0.45 mm typical)
- Angle: $0^\circ - 7^\circ$
- Dimension: (1)
- Dimension: 0.15 / 0.05

Bottom View:

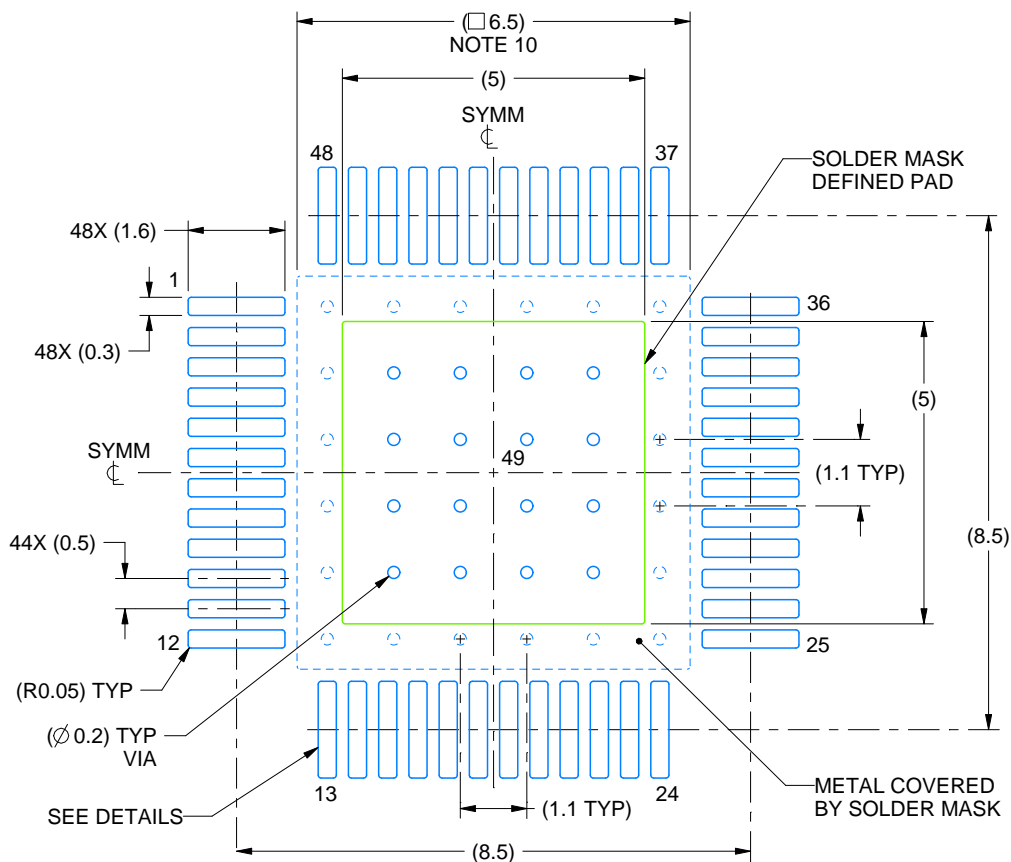
- Overall width: 5.00 mm (4.23 mm typical)
- Overall height: 5.00 mm (4.23 mm typical)
- Pin pitch: 0.25 mm (NOTE 5)
- Dimensions: 12, 13, 24, 25, 36, 37, 48, 49

PowerPAD is a trademark of Texas Instruments.

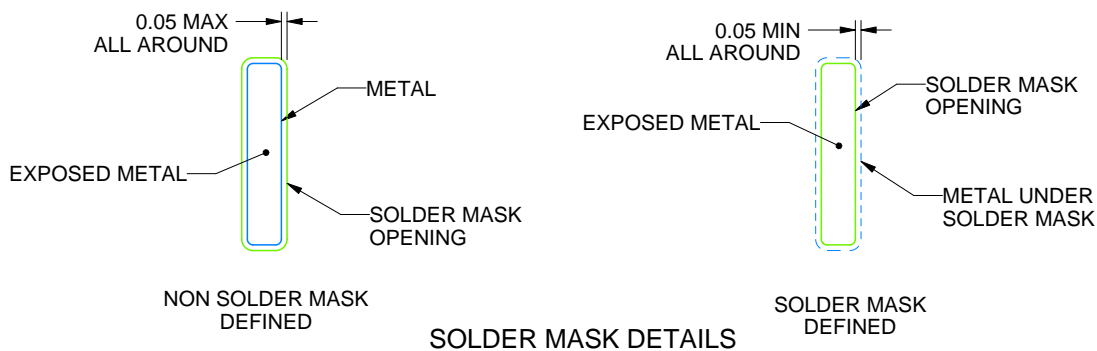
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PHP0048L**PowerPAD™ HTQFP - 1.2 mm max height**

PLASTIC QUAD FLATPACK



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



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NOTES: (continued)

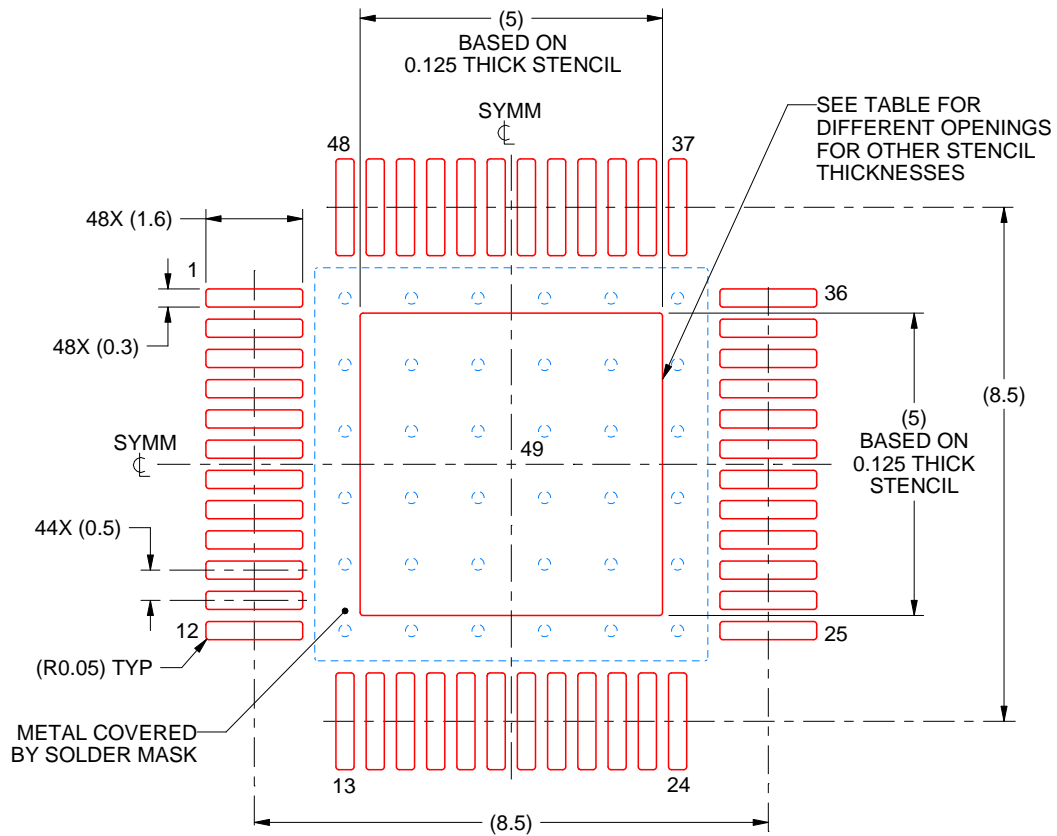
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. See technical brief, Powerpad thermally enhanced package, Texas Instruments Literature No. SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.
10. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

PHP0048L

PowerPAD™ HTQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:8X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	5.59 X 5.59
0.125	5.00 X 5.00 (SHOWN)
0.150	4.56 X 4.56
0.175	4.23 X 4.23

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

重要通知和免责声明

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